
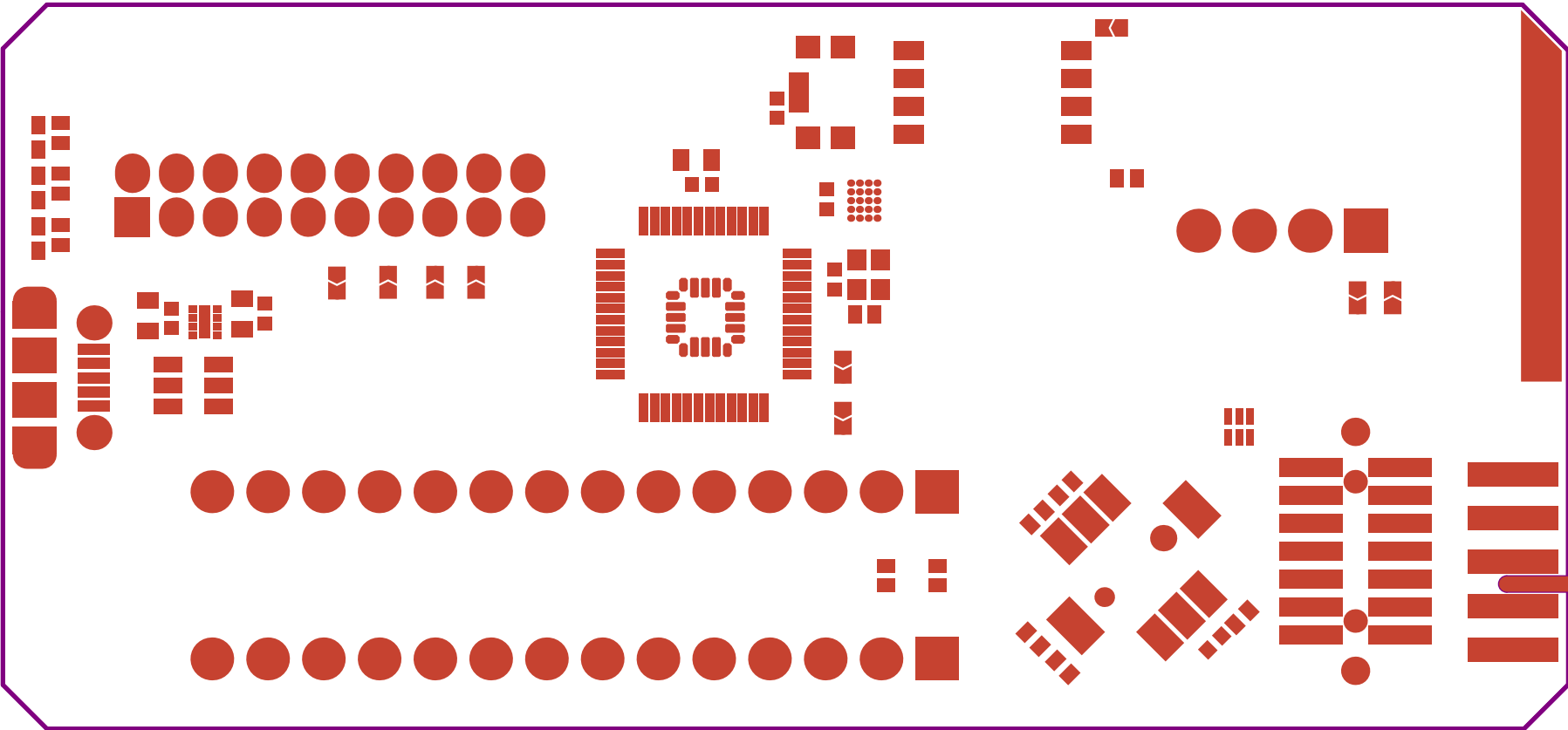

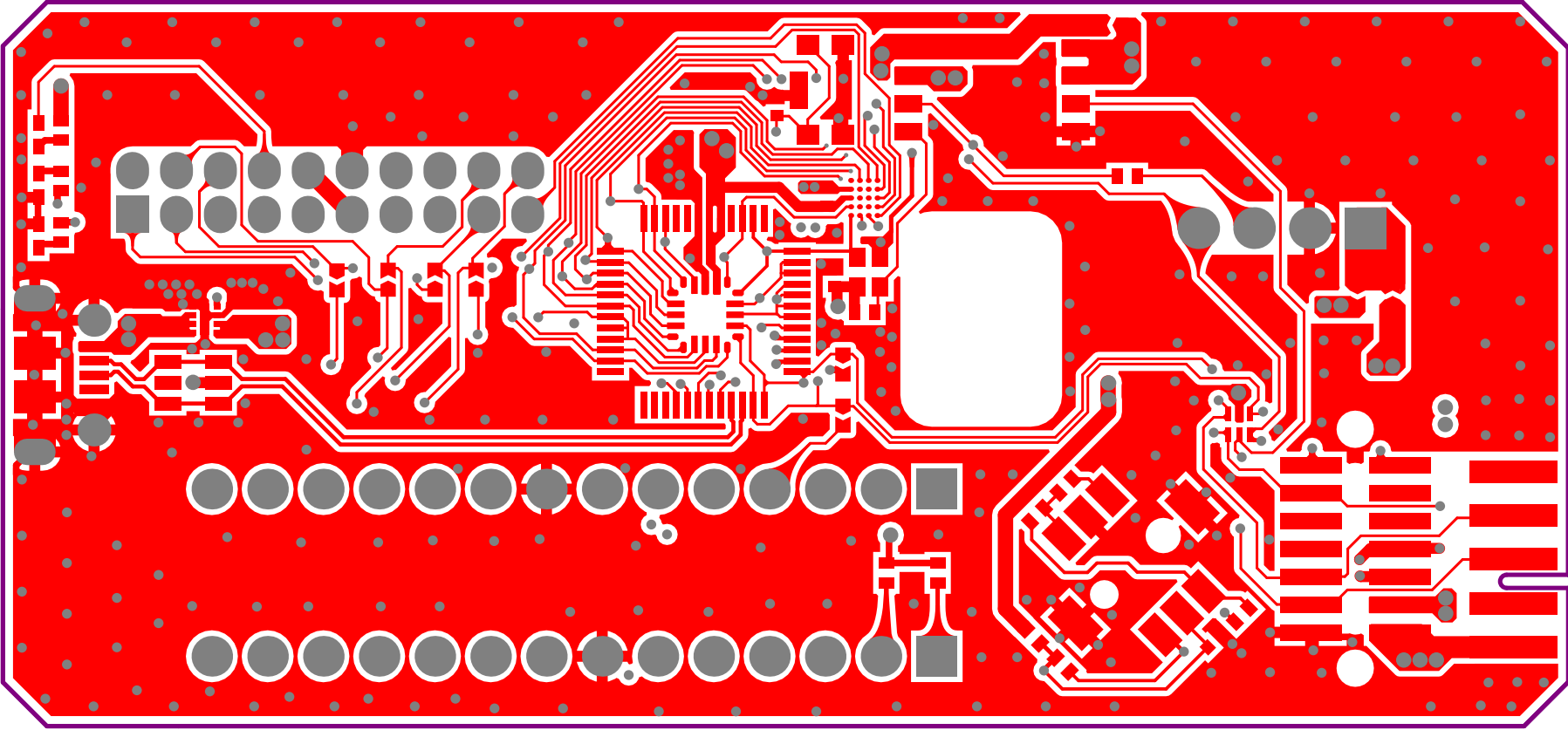



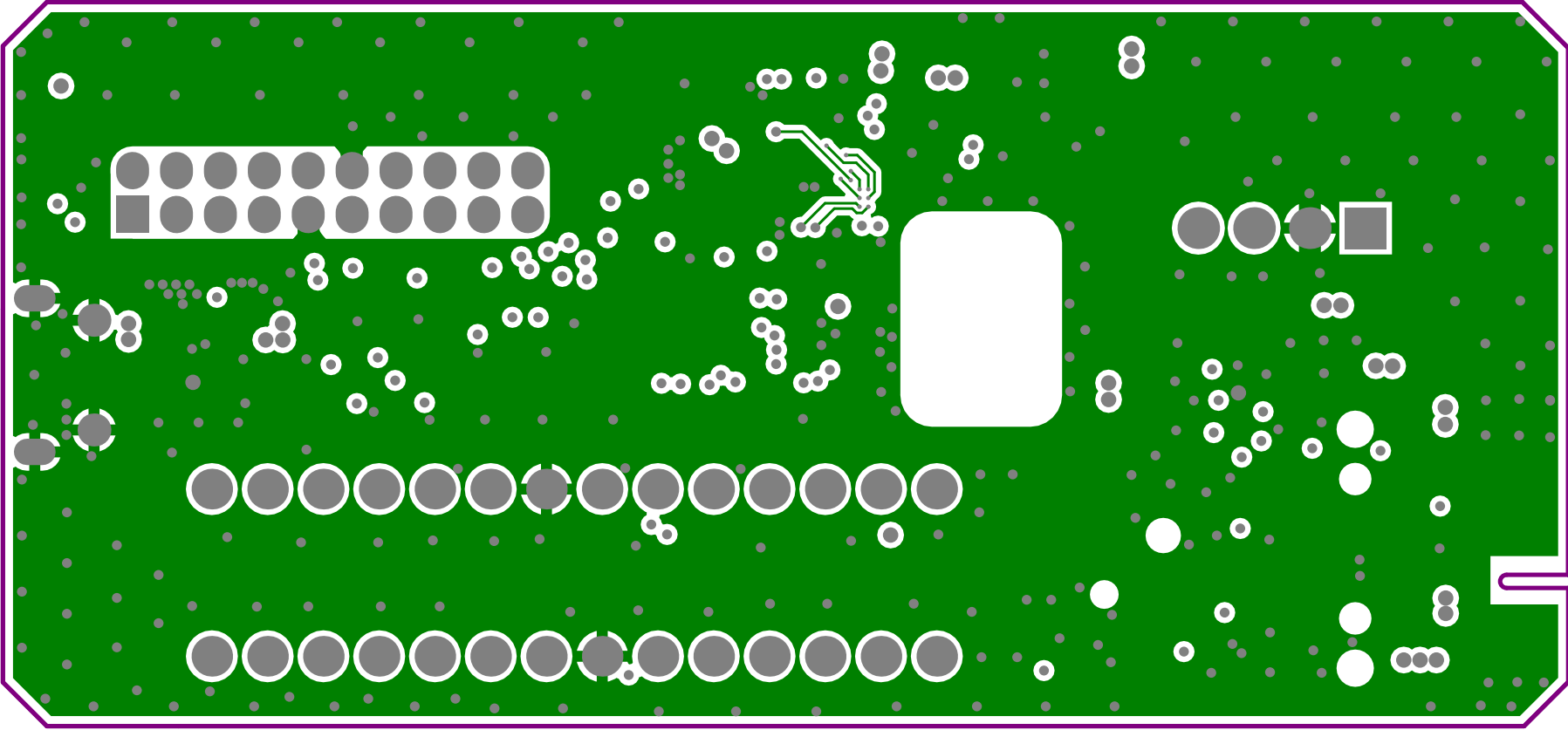
Project: STM32C0316-DK		
Layer: Top Overlay	Gerber: .GTO	
Variant: C031C6	Ref: MB1716	
Date: 13-01-21	Rev: A	




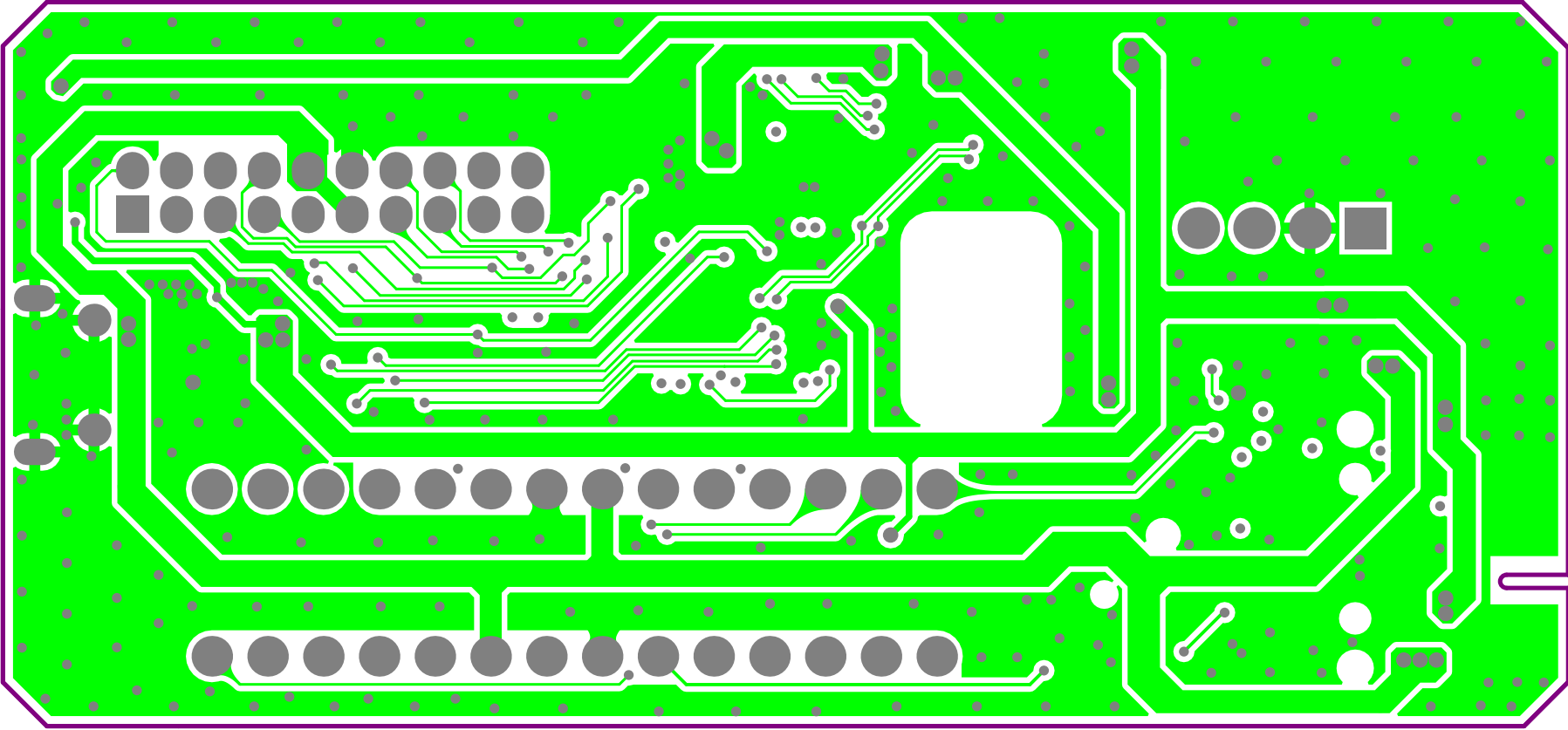
Project: STM32C0316-DK		
Layer: Top Solder	Gerber: .GTS	
Variant: C031C6	Ref: MB1716	
Date: 13-01-21	Rev: A	




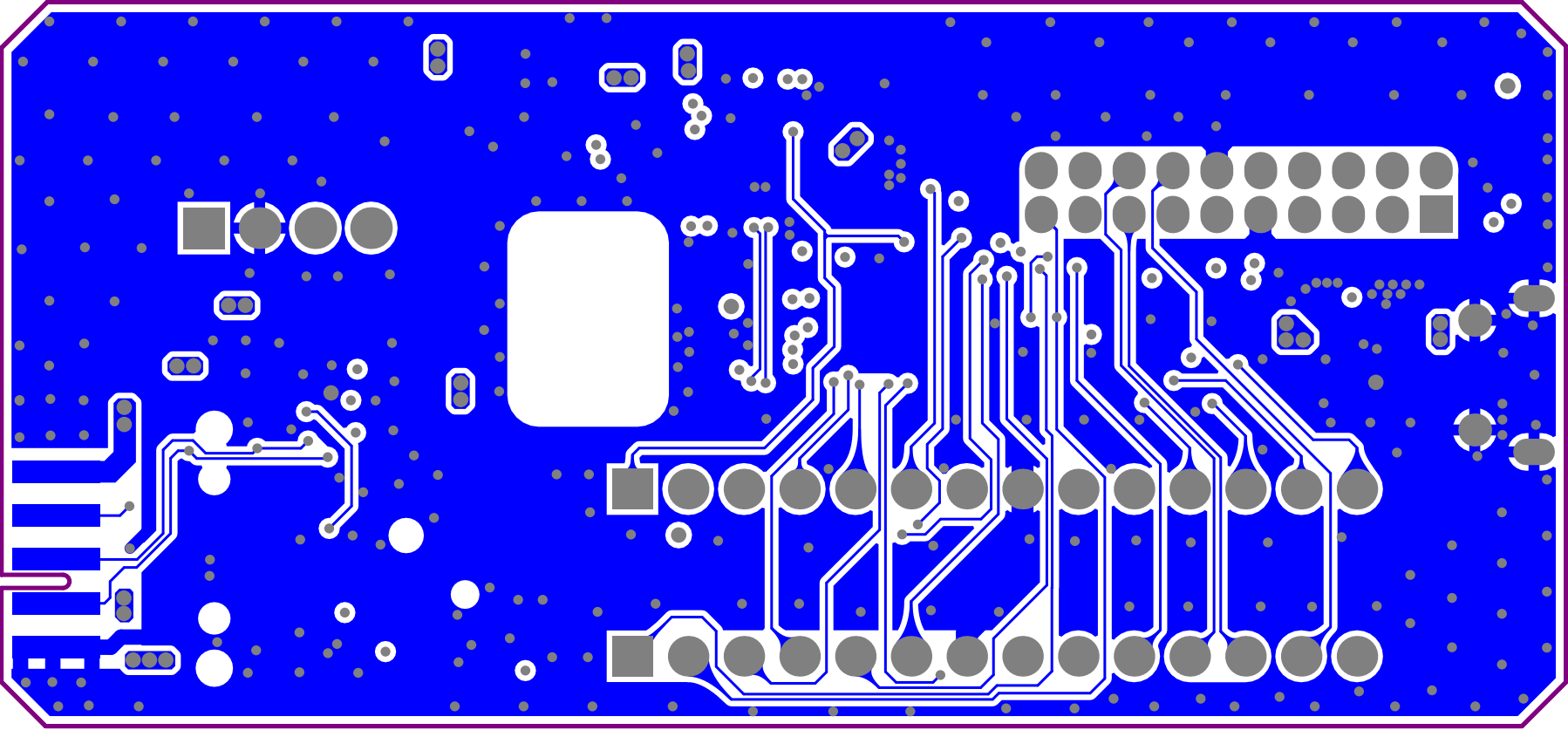
Project: STM32C0316-DK		
Layer: Top Layer	Gerber: .GTL	
Variant: C031C6	Ref: MB1716	
Date: 13-01-21	Rev: A	



Project: STM32C0316-DK		
Layer: M1 Layer	Gerber: .G1	
Variant: C031C6	Ref: MB1716	
Date: 13-01-21	Rev: A	



Project: STM32C0316-DK		
Layer: M2 Layer	Gerber: .G2	
Variant: C031C6	Ref: MB1716	
Date: 13-01-21	Rev: A	



Project: STM32C0316-DK

Layer: [Bottom Layer](#)

Gerber: [.GBL](#)

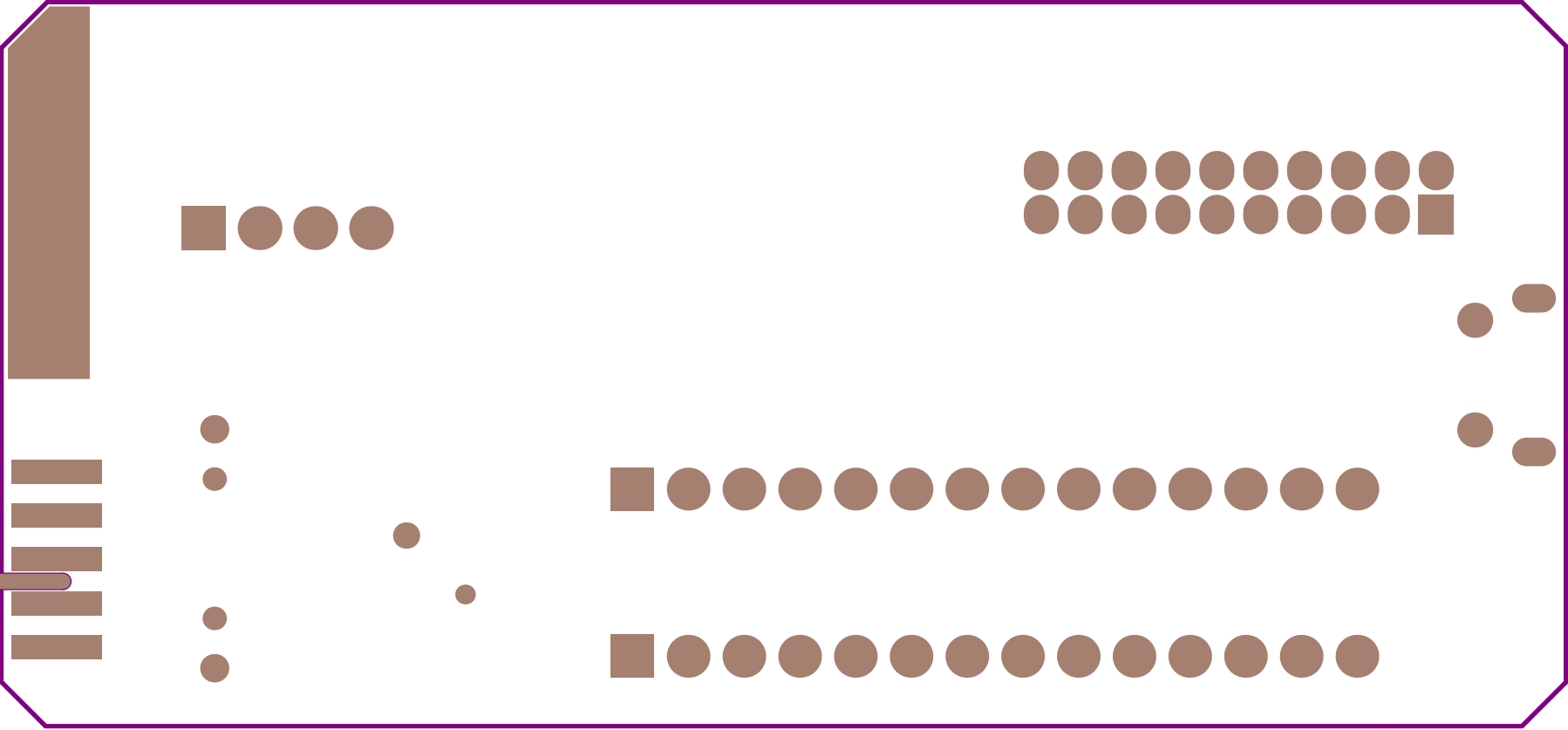
Variant: C031C6

Ref: MB1716

Date:13-01-21

Rev: A





Project: STM32C0316-DK

Layer: Bottom Solder

Gerber:.GBS

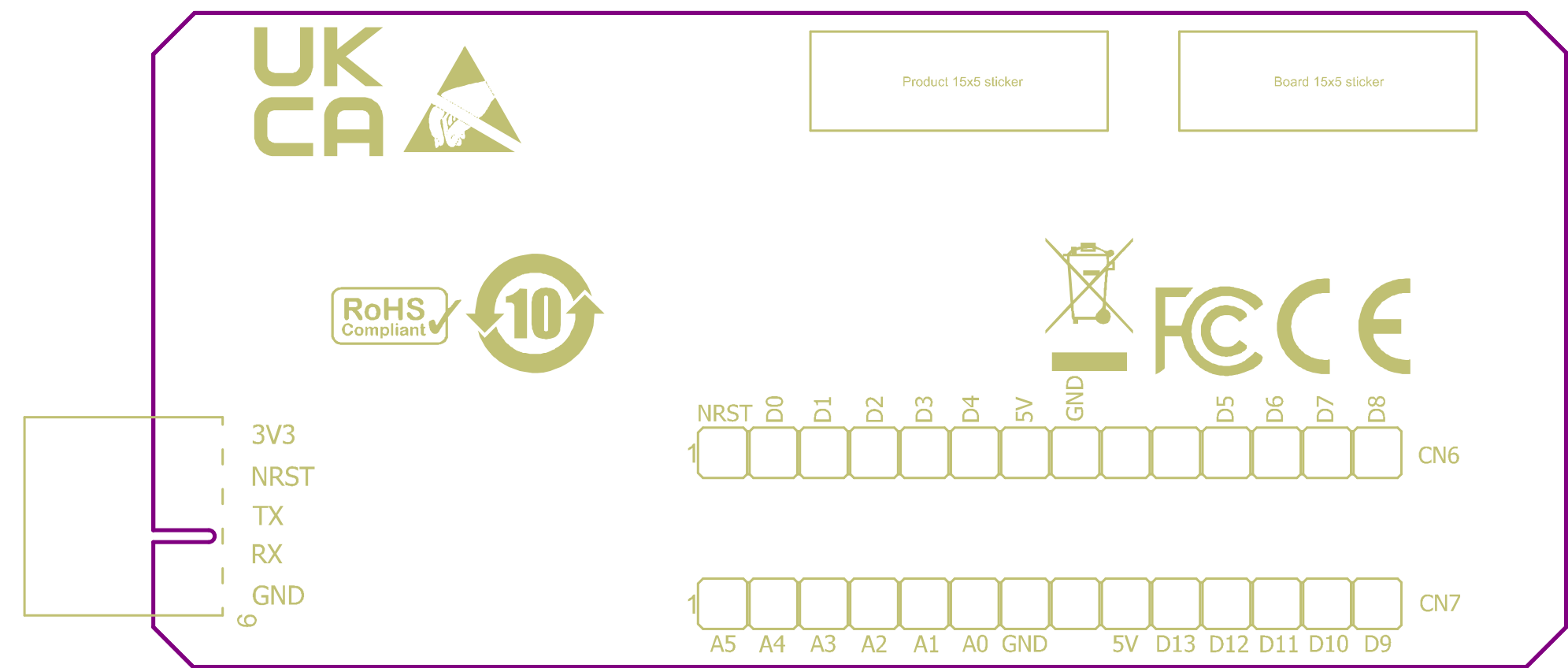
Variant: C031C6


Ref: MB1716

Date:13-01-21

Rev: A





Project: STM32C0316-DK		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: C031C6	Ref: MB1716	
Date:13-01-21	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

☐TG-170

☒TG-150

☐TG-140

N/A

☐GREEN

☐WHITE

☒BLUE

☐BLACK

☒WHITE

☐YELLOW

☐BLACK

☐Blue ink PANTONE 2955

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

☐NO

☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒SOLDERMASK

☐NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3

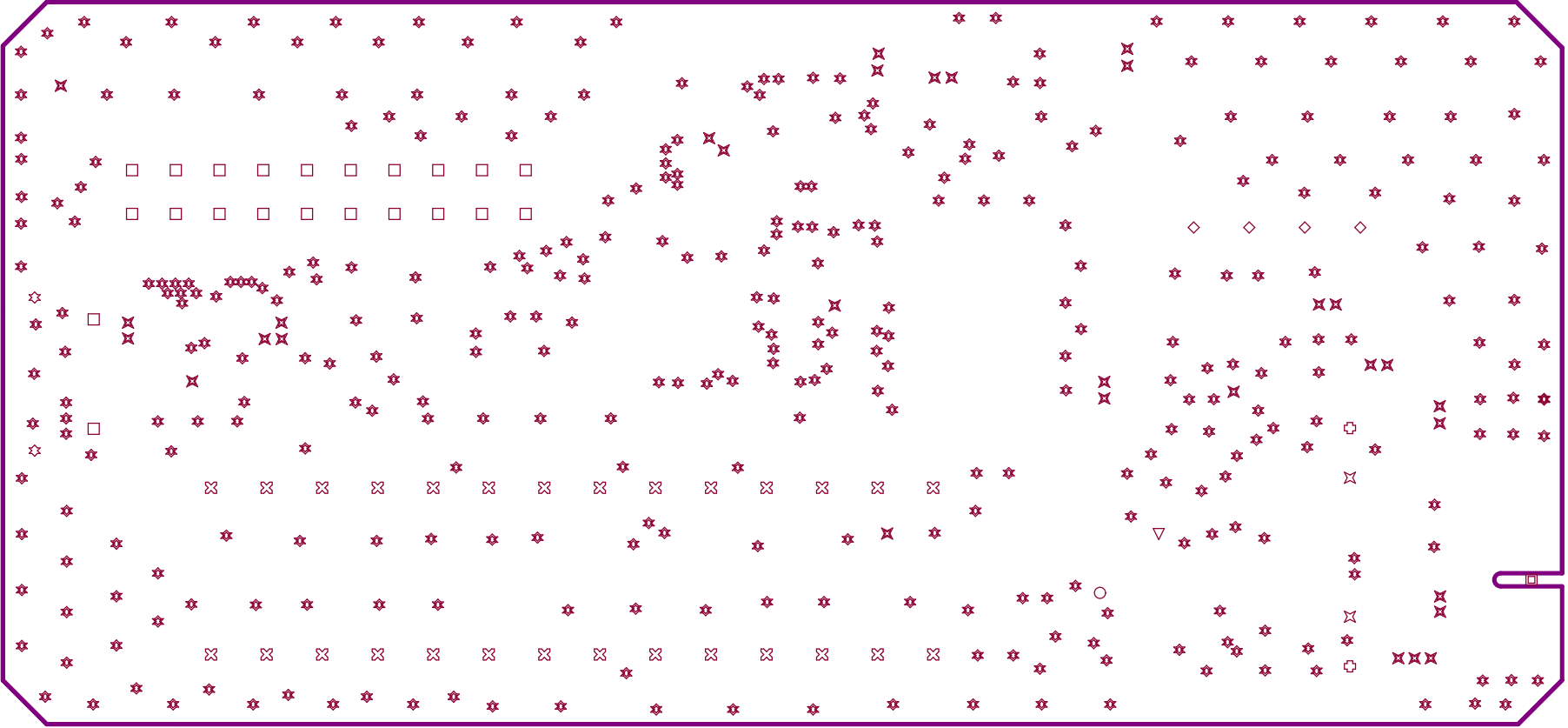
ASPECT-RATIO, AXE Z :

6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.12mm
GAPS : 0.12mm

IMPEDANCE TABLE USB					
LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	0.185	0.15	NA	90 ohm	+/- 10%



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
○	1	31.50mil (0.80mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn80m85p1000
▽	1	43.31mil (1.10mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn110m115p1000
▣	1	133.86mil (3.40mm)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn340_60m345
✱	2	23.62mil (0.60mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r190_120h60_130r100m195_125
✱	2	38.19mil (0.97mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn97m102
⊕	2	46.85mil (1.19mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn119m124
◇	4	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
◎	11	3.94mil (0.10mm)	PTH	Round	Top Layer - M1	Via	Rounded	v20h10m0
□	22	35.43mil (0.90mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
✱	28	39.37mil (1.00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)
✱	31	15.75mil (0.40mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v70h40m0mx0
✱	357	9.84mil (0.25mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
	462 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer	Copper	0.035mm		
	Dielectric 1	FR-4	0.220mm	4.2	
2	M1	Copper	0.035mm		
	Dielectric 3		1.000mm	4.2	
3	M2	Copper	0.035mm		
	Dielectric 2		0.220mm	4.2	
4	Bottom Layer	Copper	0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

Project: STM32C0316-DK

Layer: Drill Drawing

Variant: C031C6

Date: 13-01-21

Gerber: .DRL

Ref: MB1716

Rev: A

